

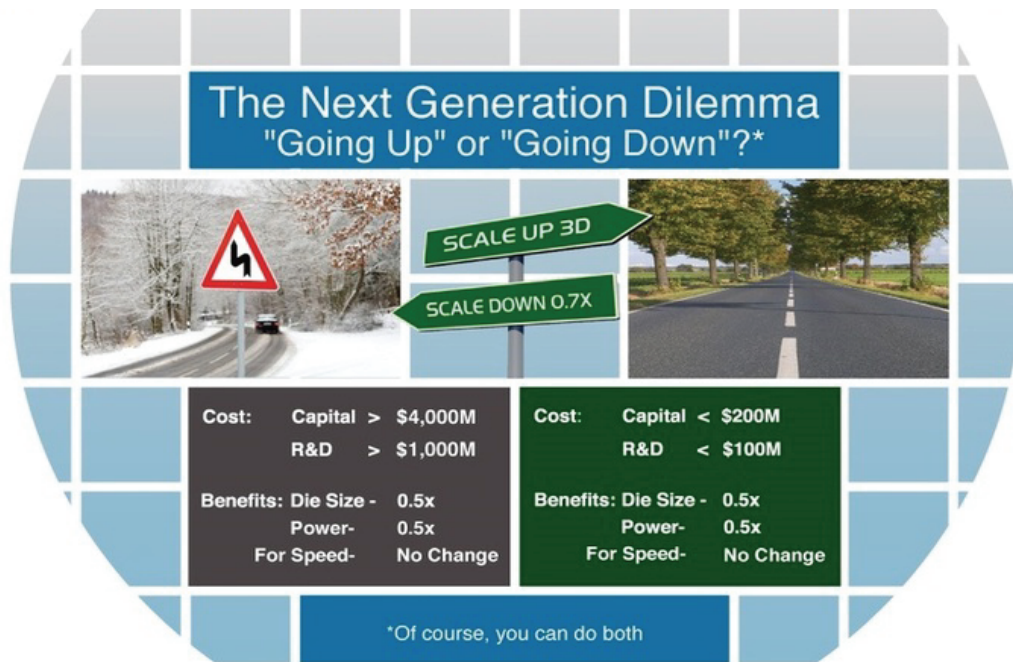


Technology Breakthrough Looking for Partners

The Monolithic 3D-IC is *finally* practical

A technology breakthrough allows the fabrication of semiconductor devices with multiple tiers of metallization connected active devices by utilizing conventional wafer fab equipment.

Monolithic 3D Inc. offers solutions for the traditional semiconductor marketplace technologies of logic and memory, and is looking to partner with electronic-photonics innovators to apply this technology to the heterogeneous integration space.



Zvi Or-Bach is the founder of Monolithic 3D™ Inc., which was originally incorporated in 2009 under the name NuPGA, with the mission to develop this path for practical monolithic 3D ICs.

Zvi Or-Bach

President and CEO



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- Winner of the EE Times Innovator of the Year Award
- Invention of
 - First Structured ASIC architecture
 - First laser-based system for one-day Gate Array customization
 - First Structured ASIC fabric
- Founder & CEO of eASIC
 - Won EE Times' 2005 ACE Award for Ultimate Product of the Year
- Founder & CEO Chip Express (now called Chipx, recently acquired by Gigoptix)
 - High-Tech Fast 50 Company for three consecutive years
- Holder of over 50 patents.